## Silicon Carbide Schottky Diode

## 650 V, 12 A

# FFSM1265A

#### Description

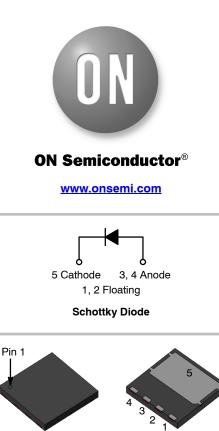
Silicon Carbide (SiC) Schottky Diodes use a completely new technology that provides superior switching performance and higher reliability compared to Silicon. No reverse recovery current, temperature independent switching characteristics, and excellent thermal performance sets Silicon Carbide as the next generation of power semiconductor. System benefits include highest efficiency, faster operating frequency, increased power density, reduced EMI, and reduced system size and cost.

#### Features

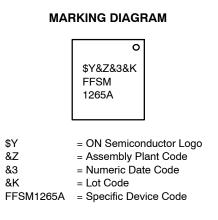
- Max Junction Temperature 175°C
- Avalanche Rated 79 mJ
- High Surge Current Capacity
- Positive Temperature Coefficient
- Ease of Paralleling
- No Reverse Recovery/No Forward Recovery
- This Device is Pb–Free, Halogen Free/BFR Free and RoHS Compliant

#### Applications

- General Purpose
- SMPS, Solar Inverter, UPS
- Power Switching Circuits



PQFN4 8X8, 2P (Power88) CASE 483AP



### **ORDERING INFORMATION**

See detailed ordering and shipping information on page 2 of this data sheet.

## FFSM1265A

Symbol	Parameter	Value	Unit	
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage	650	V	
E <sub>AS</sub>	Single Pulse Avalanche Energy (Note 1)	79	mJ	
١ <sub>F</sub>	Continuous Rectified Forward Current @ $T_C$ < $\sim$	12	А	
	Continuous Rectified Forward Current @ $T_C$ < $\sim$	12.5	А	
I <sub>F, Max</sub>	Non-Repetitive Peak Forward Surge Current	T <sub>C</sub> = 25°C, 10 μs	700	А
		T <sub>C</sub> = 150°C, 10 μs	515	А
I <sub>F,SM</sub>	Non-Repetitive Forward Surge Current	Half-Sine Pulse, t <sub>p</sub> = 8.3 ms	63	А
I <sub>F,RM</sub>	Repetitive Forward Surge Current	31	А	
Ptot	Power Dissipation	$T_{\rm C} = 25^{\circ}{\rm C}$	80	W
		T <sub>C</sub> = 150°C	14	W
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		–55 to +175	°C

#### **ABSOLUTE MAXIMUM RATINGS** (T<sub>C</sub> = 25°C unless otherwise noted)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1.  $E_{AS}$  of 79 mJ is based on starting  $T_J$  = 25°C, L = 1 mH,  $I_{AS}$  = 12.6 A, V = 50 V.

#### THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max	1.87	°C/W

#### **ELECTRICAL CHARACTERISTICS** (T<sub>C</sub> = 25°C unless otherwise noted)

Symbol	Parameter	Test Condition	Min	Тур	Max	Unit
V <sub>F</sub>	Forward Voltage	I <sub>F</sub> = 12 A, T <sub>C</sub> = 25°C	-	1.5	1.75	V
		$I_F = 12 \text{ A}, \text{ T}_C = 125^{\circ}\text{C}$	-	1.6	2.0	
		I <sub>F</sub> = 12 A, T <sub>C</sub> = 175°C	-	1.72	2.4	
I <sub>R</sub>	Reverse Current	$V_{R} = 650 \text{ V}, \text{ T}_{C} = 25^{\circ}\text{C}$	-	-	200	μΑ
		$V_{R} = 650 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	-	400	
		$V_{R} = 650 \text{ V}, \text{ T}_{C} = 175^{\circ}\text{C}$	-	-	600	
Q <sub>C</sub>	Total Capacitive Charge	V = 400 V	-	40	-	nC
С	Total Capacitance	V <sub>R</sub> = 1 V, f = 100 kHz	-	665	-	pF
		V <sub>R</sub> = 200 V, f = 100 kHz	-	74	-	
		V <sub>R</sub> = 400 V, f = 100 kHz	-	54	-	

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Numbe	r Top	Marking	Package	Reel Size	Tape Width	Shipping (Qty / Packing)
FFSM1265/	A FFS	M1265A	PQFN4 8X8, 2P (Power88)	13″	13.3 mm	3000 / Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## FFSM1265A

### **TYPICAL CHARACTERISTICS**

(T<sub>J</sub> = 25°C unless otherwise noted)

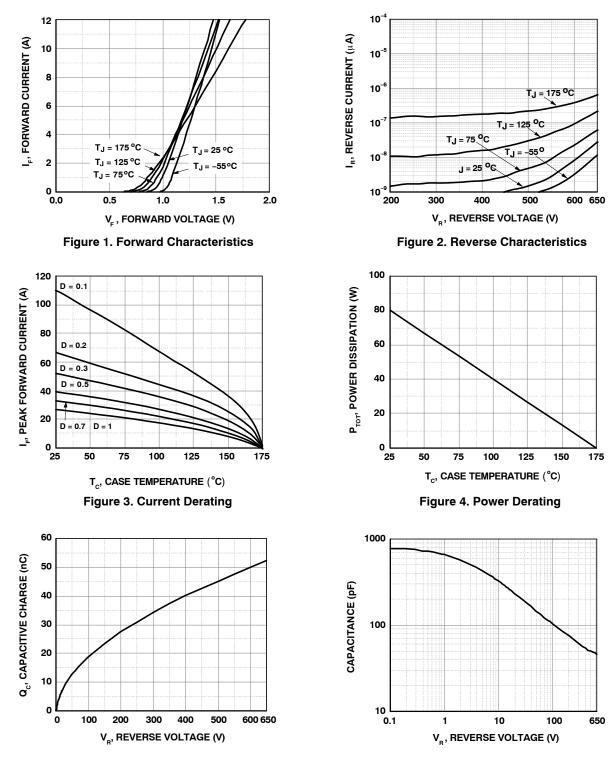


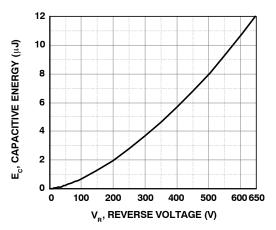
Figure 5. Capacitive Charge vs. Reverse Voltage

Figure 6. Capacitance vs. Reverse Voltage

### FFSM1265A

#### **TYPICAL CHARACTERISTICS**

(T<sub>J</sub> = 25°C unless otherwise noted)





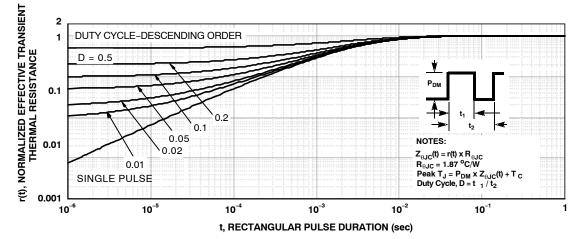
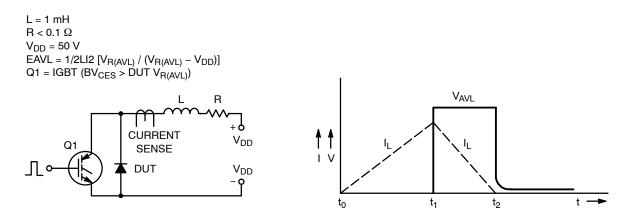


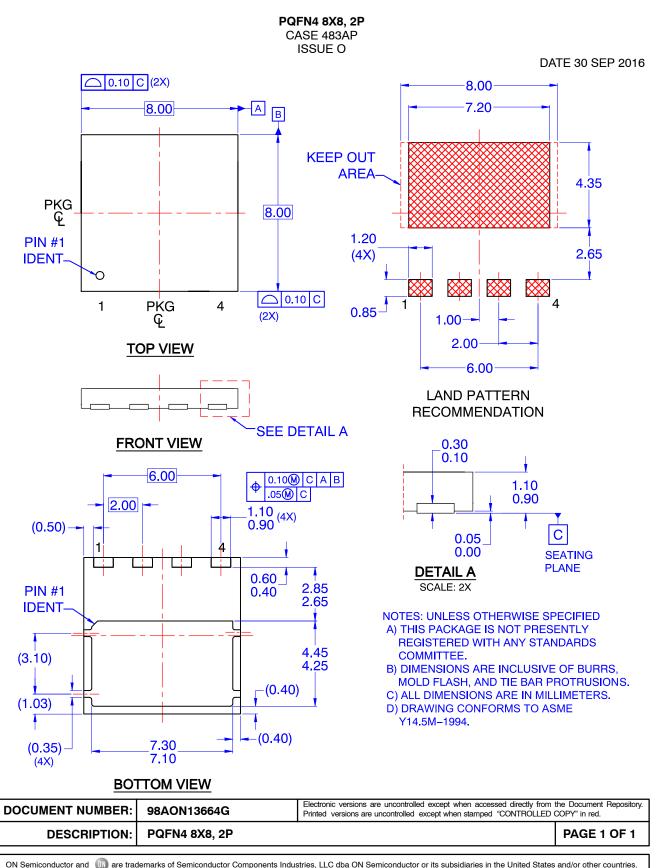
Figure 8. Junction-to-Case Transient Thermal Response Curve

#### **TEST CIRCUIT AND WAVEFORMS**









ON Semiconductor and () are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. ON Semiconductor does not convey any license under its patent rights nor the right or there.

ON Semiconductor and are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at <u>www.onsemi.com/site/pdf/Patent-Marking.pdf</u>. ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor date sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use a a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor houteds for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries

#### PUBLICATION ORDERING INFORMATION

#### LITERATURE FULFILLMENT:

#### TECHNICAL SUPPORT

ON Semiconductor Website: www.onsemi.com

Email Requests to: orderlit@onsemi.com

North American Technical Support: Voice Mail: 1 800–282–9855 Toll Free USA/Canada Phone: 011 421 33 790 2910 Europe, Middle East and Africa Technical Support: Phone: 00421 33 790 2910 For additional information, please contact your local Sales Representative